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Opportunity for Advanced Computing

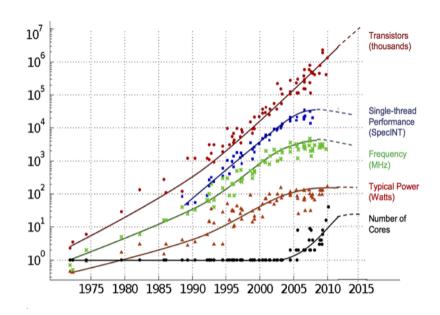
Technological Improvements are Needed Today!

Silicon Computing Challenges

- Diminishing returns in node changes
- Power, heat, clock and dark silicon limitations
- Economic hurdles to state of the art

RQL for Beyond Silicon Computing

- Reciprocal Quantum Logic
- 50-300X improvement in FLOPS/watt
- Suitable for supercomputing & data centers
- · Provides a path beyond exascale



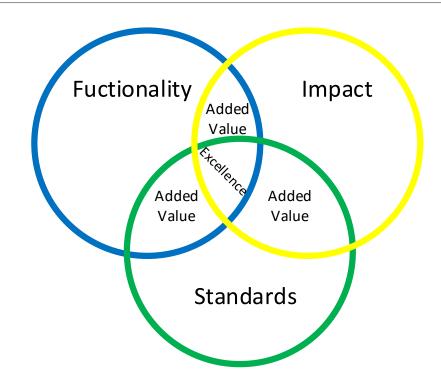
Original data collected and plotted by M. Horowitz, F. Labonte, O. Shacham, K. Olukotun, L. Hammond and C. Batten Dotted line extrapolations by C. Moore



Superconducting Architecture Goals

Questions to answer

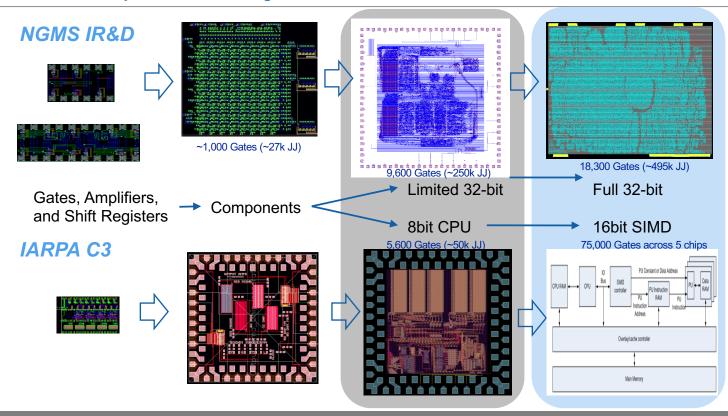
- Re-Map or Re-Think
- Technology's influence on Architecture
- RQL vs CMOS metrics
 - Area, performance, power
- Prototype RQL architecture
- Analysis of Architecture



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RQL Digital Progression

3 years of Continuous Improvement in Design, Fab and Test



RQL for Architects



Basic RQL Properties

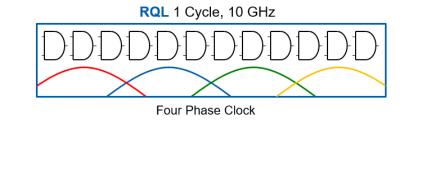
Lossless, fast wires
Non-inverting basic gate
Low switch power
Low gate gain (fanout)
Resonator clock
Power from AC clock
Requires low temp

смоѕ	Data Encoding	Active Element	Performance	Gate Density	Wiring
T1 T2 NAND y	Voltage 1.3V 300 ps	n- and p-type Silicon transistors 10 ⁻¹⁵ Joules Switching Energy	Driven by <u>Litho</u> Node, Supported by Material	Driven by <u>Litho</u> Node	Resistance & Capacitance Driven Energy Intensive
RQL	Data Encoding	Active Element	Performance	Gate Density	Wiring
	Current Pulse or Junction Phase 0.001V 2 ps	Superconductor -Insulator Tunnel Junction 10 ⁻¹⁹ Joules Switching Energy	Driven by Materials NOT <u>Litho</u> Node	Driven by metal- insulator Layer Count and Litho Node	Inductance Driven Lossless Transmission



RQL Layout and Timing

- Gates compatible with tools
- Gate performance relative to resonator power
 - More phases, better perf
- Latch based timing
- No physical latch boundary
- Supports 2-4x frequency



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12 Gates per clock @ 10 GHz



0.2 ns -

Logic Depth

24

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24

CMOS

24 Gates per clock @ 5 GHz



RQL Design Methodologies

Return to Zero (Wave Pipeline)

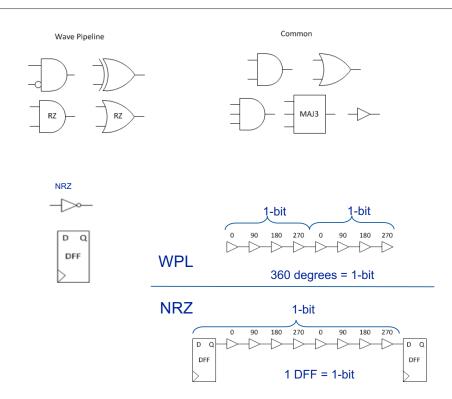
- Very high throughput
- Data always moving
- Runs at AC clock/power rate

Non-Return to Zero (NRZ)

- CMOS-like design style
- Traditional controllable clock
- Lower Logic Power (sometimes)

Interfacing is relatively simple

Hybrid design best of both approaches





Wave pipeline Inverter

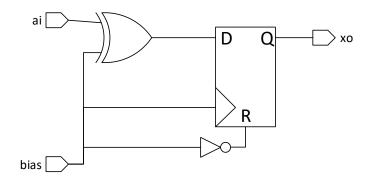
WPL inverter based on an XOR

Equivalent circuit for what it actually does

Means an AC phase boundary is needed at every one of these

More phases means less penalty waiting for boundary

NRZ has true inverter





Interconnect: Fast and Virtually Free

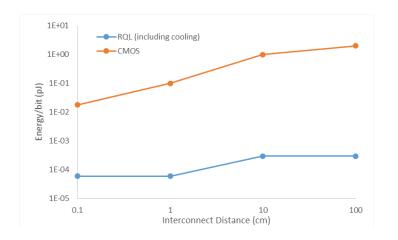
Large superconducting computers competitive in density per **volume** rather than area

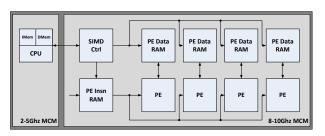
RQL feature size drive multi-chip implementations so MCM support is critical

Need PTLs to efficiently communicate between chips on MCM

PTLs between blocks avoid timing penalties that reduce performance

Efficient, low latency long distance wires - major advantage over CMOS







Superconducting Memories

NDRO

- Large Cell (device limited)
- Timing per bit doesn't support high performance for large arrays

77K DRAM

- DRAM technology for high density
- 77K for lower power
- Good bulk memory solution

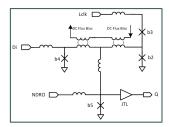
Other technologies being explored

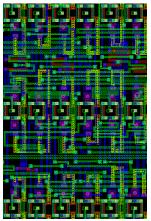
- SRAM like timing and density under development (L1/L2 cache)
- Magnetic RAM for high density (L3 cache)

Faster wires mean smaller caches possible

Low power wires mean more, wider busses possible

NDRO RAM







RQL Compute Density

100x compute density regardless of architecture at large scale

 Applies to CPUs/GPUs/FPGAs or special purpose processors

CMOS 3U rack mount vs RQL

- 3U spacing for heat dissipation
- RQL spacing: 7-8 mm
- >15x volume advantage

3D stacking

Favorable RQL thermal properties

1000x CMOS wire power vs RQL

- 1.3V CMOS vs 0.001V RQL
- Power function of V²

	Initial Node		Future Node		
	CMOS	RQL	CMOS	RQL	
Processor	244.0	1	165.0	1	
Chip/MCM	2.6	1	1.8	1	
Board	1.3	1	1.0	2	
Rack	1.0	96	1.0	142	



Architectural Opportunities

Point-to-point vs Shared busses

RQL wire power, delay advantage

Frequency vs Performance

• Data flow, Pipelines 10+ GHz

Single Chip vs Multi-chip

Chip-to-Chip penalties lower in RQL

Memory Hierarchy

Size vs Speed trade-off

Fanout

 MUX Selects, High fanout control, reset

Inversion

• Dual rail, Synthesis reduction

Routing

JTLs more dense vs PTLs faster

Wave-pipelined vs NRZ

Balance performance and area/power

Revisit CMOS Axioms

- Pipeline FIFOs rather than stalls
- Crossbar switches rather than shared busses
- Data flow rather than control flow



Conclusions

Attributes to take advantage of:

- At speed, wave-pipelined nature of RQL means we get clock scaling back
- Nearly free resistive interconnects means high cross sectional bandwidth networks are now a large routing problem
- Scaling to large (160x240mm) "systems on a chip" vs multichip for dense compute capability at much lower power
- Non-von Neumann architectures spiking neural networks seem like a natural fit for single flux quanta pulses

Heterogeneous computing is also possible

Similar to what we see now with GPUs, FPGAs, Xeon Phi, etc.

A new era of computer architecture required for RQL

 From small A – micro-architecture to big A – system level architecture

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